

PATENTS



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hao-Wen CHIU et al.

Serial No. 10/015,587

GROUP 1731

Filed December 17, 2001

Examiner Unassigned

#4
HW
8-1002

MOLD AND A METHOD OF HOT-FORMING A THERMOPLASTIC LENS

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying documents, copies of which are attached to this statement, are made of record on the enclosed sheet.

A concise explanation of the relevance of these items is that these references were discovered during any searches they or their client had made, or that they were considered in the preparation of the application.

Respectfully submitted,

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By

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FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE
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SERIAL NO.
10/015,587

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Use several sheets if necessary)

APPLICANT
Hao-Wen CHIU et al.

FILING DATE
December 17, 2001

GROUP
1731

35 CFR 1.98(b)

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	5,376,317	12/94	MAUS et al.			
	AB	5,458,820	10/95	LEFEBVRE			
	AC						
	AD						

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

		DOCUMENT NO.	PUBL. DATE	COUNTRY OR PATENT OFFICE	CLASS	SUB CLASS	TRANSLATION YES NO
	AI	99/24243	05/99	WO			
	AJ	2 525 525	10/83	FR			English abstract
	AK						
	AL						
	AM						
	AN						
	AO						
	AP						
	AQ						

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

	AT	
	AU	
	AV	
	AX	
	AY	

EXAMINER

DATE CONSIDERED

EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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